



BREST FRANCE



22nd IEEE WORKSHOP ON SIGNAL AND POWER INTEGRITY

SPI 2018



CALL FOR PAPERS

22-25 MAY 2018

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22nd IEEE WORKSHOP ON SIGNAL AND POWER INTEGRITY, 22-25 MAY 2018, BREST, FRANCE

Over the past two decades, the IEEE Workshop on Signal and Power Integrity (SPI) has evolved into a forum of exchange on the latest research and developments on design, characterization, modeling, simulation and testing for Signal and Power Integrity at chip, package, board and system level. The workshop brings together developers and researchers from industry and academia in order to encourage cooperation.

In view of the past years' success, the Committee is looking forward to the 22nd Edition which will be hosted in the charming region of Brittany, in Western France, in the city of Brest, bathed by the Atlantic Ocean. The SPI 2018 technical program will include both oral and poster sessions. A number of prominent experts will be giving tutorials on areas of emerging interest. The Conference Proceedings will be published with an ISBN code and will appear in IEEEXplore.

The SPI 2018 workshop is jointly organized by the Université de Bretagne Occidentale, the Ecole Nationale d'Ingénieurs de Brest and the Université de Savoie Mont Blanc.

<https://spi2018.sciencesconf.org>

Topics of Interest

- Modeling and simulation for SI/PI
- Coupled signal and power Integrity analysis
- Noise reduction and equalization techniques
- High-speed link design and modeling
- Power distribution networks
- RF/microwave/mixed signal systems
- 3D IC and packages (TSV/SiP/SoC)
- Nano-interconnects and nano-structures
- Electromagnetic theory and modeling
- Transmission line theory and modeling
- Macromodeling, reduced order models
- Electromagnetic compatibility
- Design methodology/flow measurements
- Jitter and noise modeling
- Stochastic/sensitivity analysis
- Electro-thermal modeling
- Chip-package co-design
- Novel CAD concepts
- Optical interconnects



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IMEP-LAHC

Important Dates

Paper submission (2-4 pages):

January 19th, 2018

Notification of acceptance:

March 2nd, 2018

Industry forum

Building on the success of previous editions, the **Industry Forum** is becoming an SPI tradition. This special session will be reserved to both invited and contributed talks from the industry. The objective is to present and discuss problems rather than solutions, for those aspects of Signal and Power Integrity (and related topics) that have no good solution yet, neither theoretical, nor in form of EDA tools. The explicit goal is to foster the discussion between industry, academia, and tool vendors, so that the three communities can cooperate in the future and focus on the most relevant problems.